

ABSTRACT OF THE DISCLOSURE

A case for dissipating heat from an electronic device is provided. The case includes an electronic circuit board with a heat generating electronic component installed thereon. A shield is positioned over the electronic component to protect it from electromagnetic interference. The shield includes an aperture through its top surface. A heat transfer conduit is molded into and through the aperture to contact the top surface of the heat generating electronic component. Outer housing, which is made of a thermally conductive material, is placed into contact with the top surface of the heat transfer conduit which extends outside the shield. As a result, heat is dissipated from the electronic component and through the housing of the electronic device via the heat transfer conduit while shielding the electronic component from electromagnetic interference.